

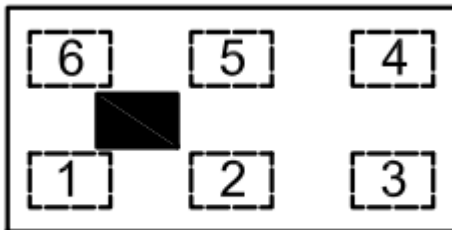
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

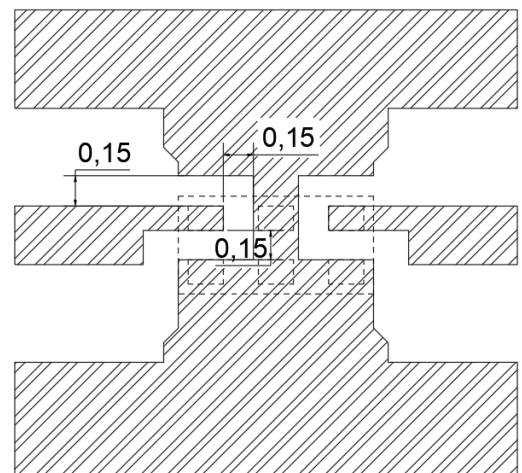
NO.	Parameter	SPEC
1	Frequency range	746-787 MHz
2	Insertion Loss	0.6 dB max.
3	Attenuation	30 dB min. @ 1554~1610 MHz 25 dB min. @ 2238~2361 MHz
4	Ruture Loss (In BW)	10 min
5	Port Impedance	50Ω
6	Operation Temperature Range	-40℃ ~ +85℃

Construction



PIN	Connection
1	NC
2	GND
3	NC
4	Input port /Output port
5	GND
6	Input port /Output port

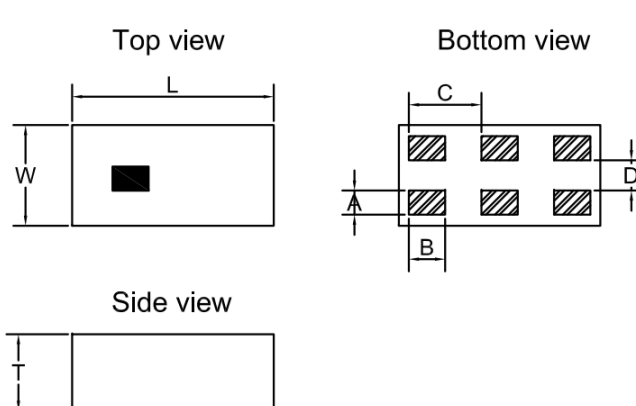
Mounting Considerations



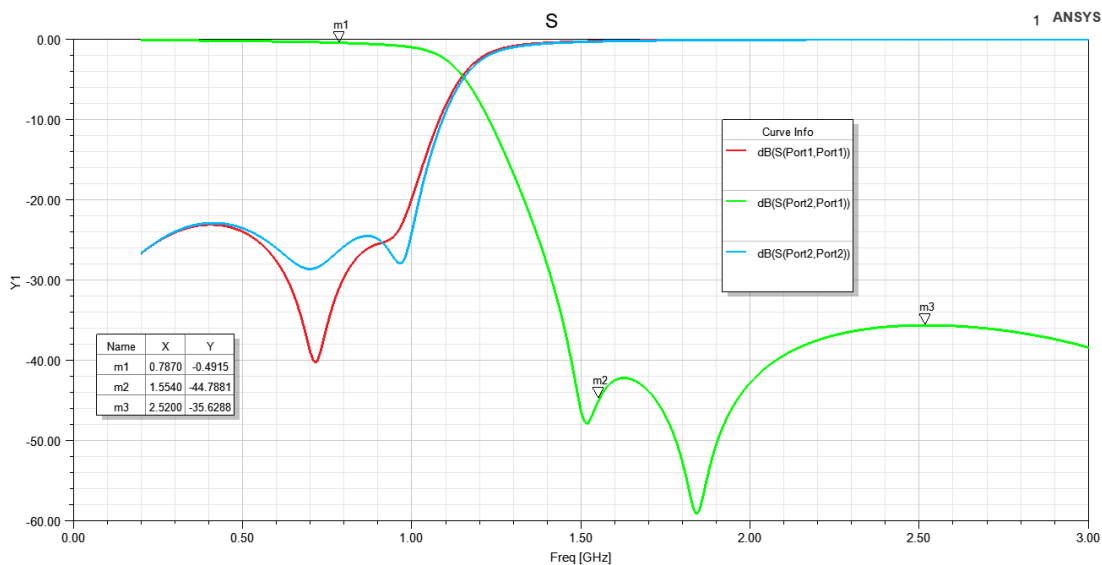
Unit: mm

Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

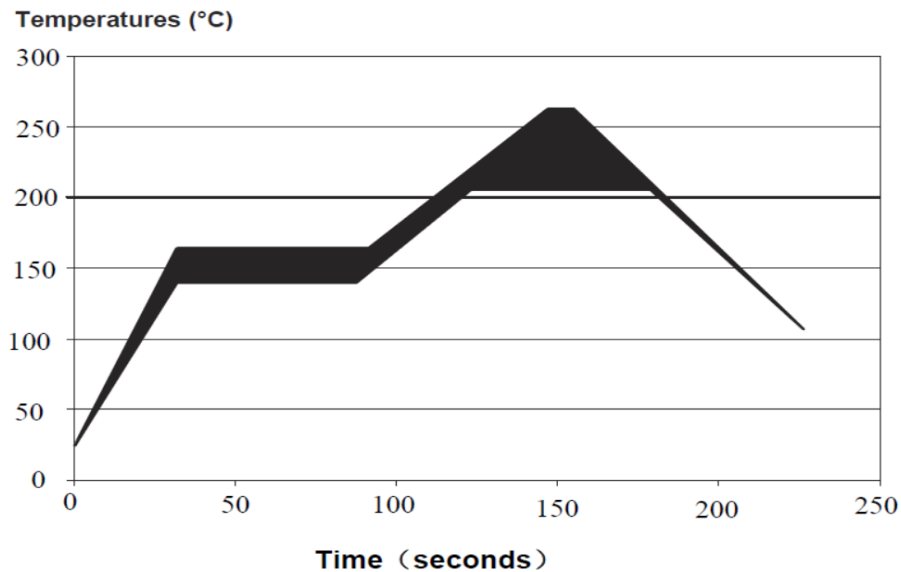
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.0 ± 0.1
	W	0.5 ± 0.1
	T	0.38 ± 0.1
	A	0.125 ± 0.1
	B	0.18 ± 0.1
	C	0.36 ± 0.1
	D	0.15 ± 0.1

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.